

Date: 2007.03.27

Specifications for Approval

Model name	:	LMG122322A-YTDSYW-NN	REV: A

Description : LIQUID CRYSRAL DISPLAY MODULE

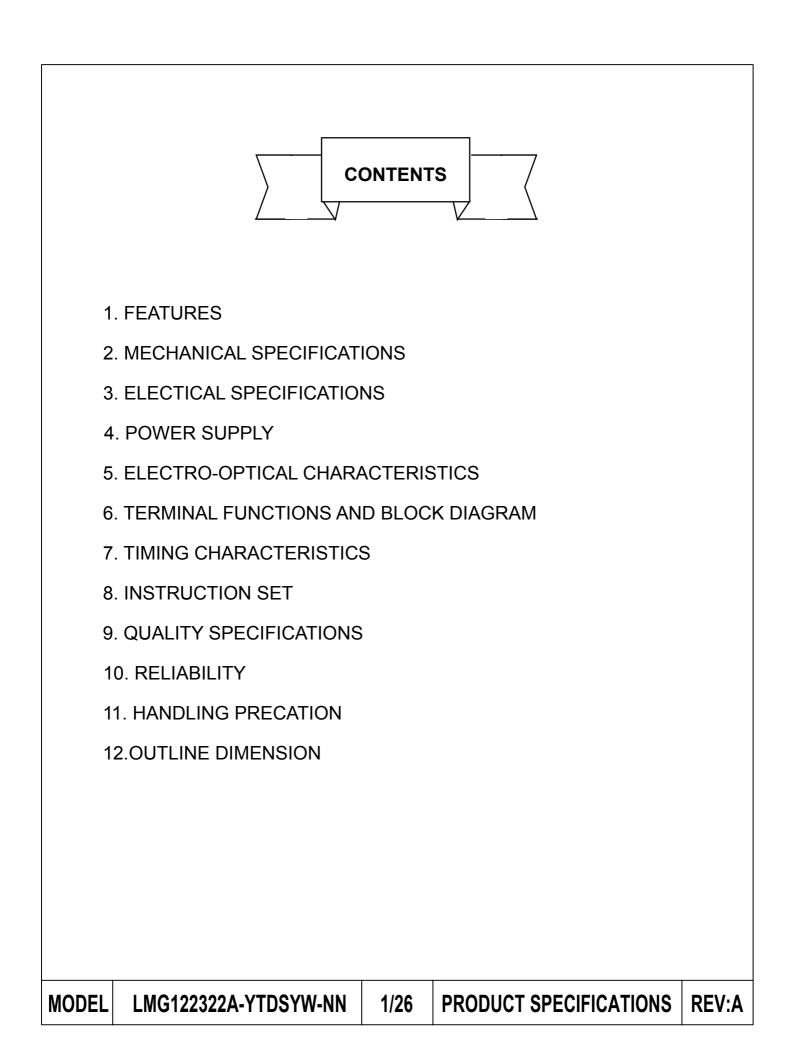
DESIGN	CHECK	APPROVED
EVEN	LYDIA	

Customer Approval	Accept Reject Comment:
	Approved by:

LCM MODULE NUMBERING SYSTEM

PART NUMBER: LMAx.....yB-CDEFGHI-JK

L: LONDA TECHNOLOGY M: MODULE **DISPLAY CONTENTS C--- CHARACTER TYPE** A: **G---** GRAPHIC TYPE **S---SEGMENT TYPE CHARACTERS Vs. LINES FOR CM** X.....: **COLUMNS Vs. ROWS FOR GM** SERIALS NUMBER FOR SM **DISTRIBUTE ACCORDING TO SIZE** y: **B**: **VERSION OF PCB C: LCD TYPE:** Y---YELLOW STN G---GRAY STN B---BLUE STN F---FSTN **T---TN D: POLARIZER TYPE: R--- REFLECTIVE T--- TRANSFLECTIVE** M---- TRANSMISSIVE **E: VIEWING TEMPRETURE:** U--- 12:00 D--- 6:00 L--- 9:00 R---- 3:00 **F: BACKLIGHT TYPE:** D---BOTTOM LED S---SIDE LED E--- EL C--- CCFL N---NO BACKLIGHT **G: COLOR OF BACKLIGHT :** Y---YELLOW/GREEN G--- GREEN **B---** BLUE **O---- ORANGE** W--- WHITE A---- AMBER **H:OPERATING TEMPRETURE:** N--- NORMAL, W--- EXTENDED , X:ESPECIALLY EXTENDED I: DENOTE DIFFERENT CHARACTER TABLE: NORMAL ELLIPSIS, T--- TAB, G--- COG -JK: FOR CM: J: IC TYPE: A--- KS0066U B--- SPLC780 **K: CHARACTER STOREROOM SEQUENCE NUMBER** FOR GM: **J: BACKLIGHT DRIVER** Y---- WITH N--- WITHOUT **K: DC-DC CONVERTER** Y--- WITH N--- WITHOUT



1 FEATURES

The features of LCD are as follows

- * Display mode : STN, Positive. Transflective
- * Color : Display dot : Blue-Black

Background: Yellow-Green

- * Display format : 122 Dots X 32 Dots
- * Interface Input Data : 8-Bit
- * Driving Method : 1/32Duty, 1/6Bias
- * Viewing Direction : 6 O'clock
- * Backlight : Yellow-Green
- * Drive IC : SED1520 (or EQUIV.)

2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	80(W) x 36(H) x 13.5(T)	mm
Number of Dots	122(W) x 32(H) Dots	mm
Viewing Area	60.5(W) x 18.5 (H)	mm
Effective display area	53.64(W) x 15.64(H)	mm
Dot Size	0.40(W) x 0.45(H)	mm
Dot Pitch	0.44(W) x 0.49(H)	mm

3. ELECTRICAL SPECIFICATIONS

3-1 ABSOLUTR MAZIMUM RATINGS (Ta = 25 °C)

ltem	Symbol	Sta			
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd – Vss	0	_	6.5	V
Supply Voltage For LCD Drive	V _{OP} = VDD – V0	0	-	13	V
Input Voltage	V1	Vss	-	Vdd	V
Operating Temp.	Тор	-20	-	+70	°C *
Storage Temp.	Tst	-30	I	+80	°C

*. NOTE: The response time will be extremely slow when the operating temperature is around -20° C, and the back ground will become darker at high temperature operating.

PRODUCT SPECIFICATIONS

3-2 ELECTICAL CHARACTERISTICS

Item		Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply Voltage		Vdd - Vss		2.4	5.0	7.0	V
LCD Dr	LCD Drive			3.5	-	13	V
"H" Level		V IH	VDD=5.0V±5%	VSS+2.0	-	Vdd	V
Input Voltage	"L" Level	V IL		VSS	-	VSS+0.8	V
Frame Frequency		fFLM	VDD =5.0V	-	-	2K	ΗZ
Current Consumption		IDD	VDD =5.0V VDD-V0=9.2V		1.60	3.0	mA
	•		V/R=160Kohm				

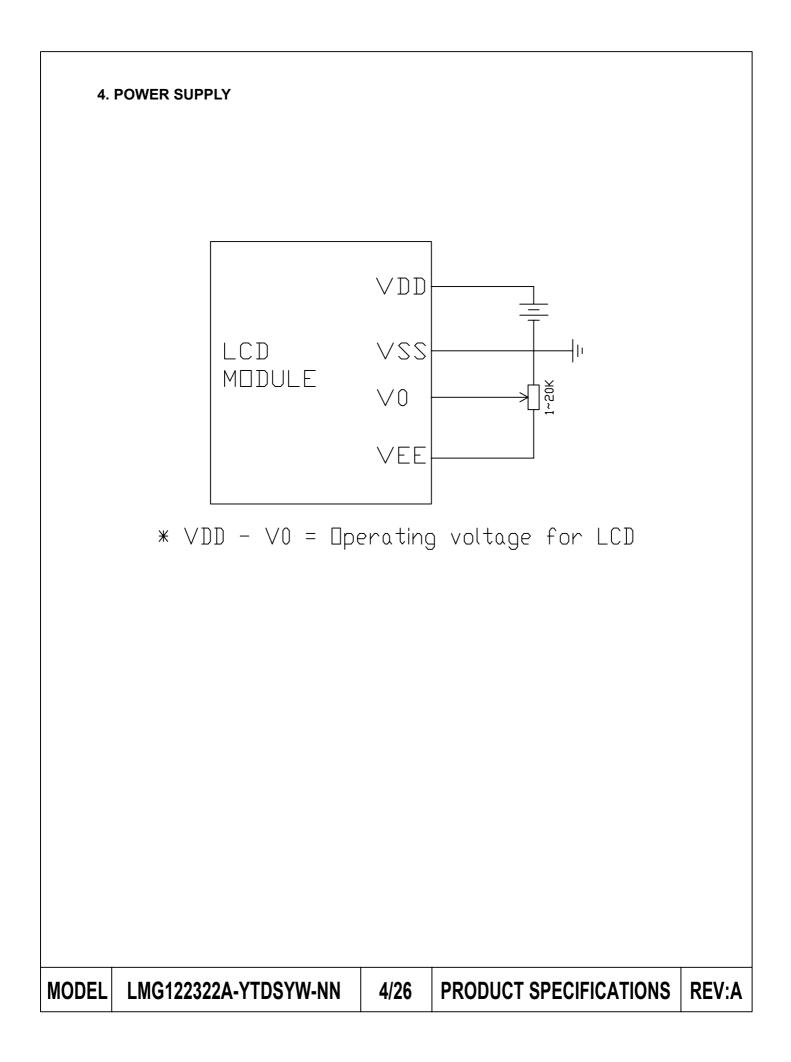
3-3. BACKLIGHT

3-3-1. Absolute Maximum Ratings

ltem	Symbol	Condition	Min.	Тур.	Мах	Unit
Forward Current	IF	Ta= 25 ℃	-	30	40	mA
Reverse Voltage	VR		-	-	8	V
Power Dissipation	PD	Ta= 25 ℃	-	-	200	mW

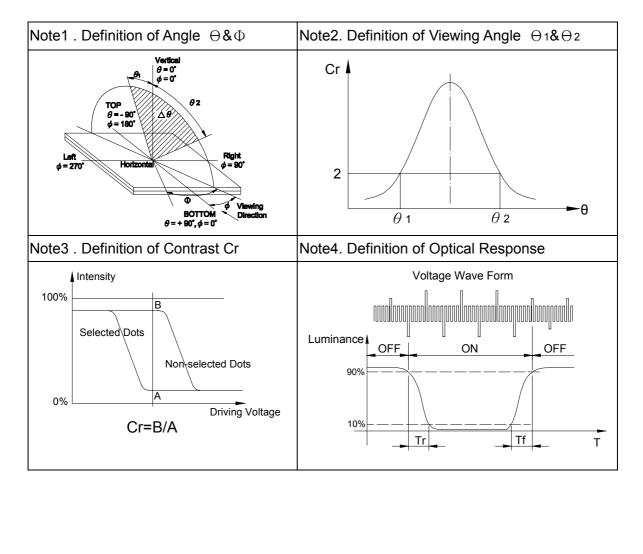
3-3-2. Opto-electronic Characteristics

ltem	Symbol	Condition	Min.	Тур.	Max	Unit
Forward Voltage	VF	Ta= 25 ℃	-	5.0	5.5	V
Luminous	-	IF= 30mA	35	-	-	cd/m²



Item	Symbol	Temp.	Min.	Тур.	Max.	Unit	Conditions	Note
Viewing	⊖2–⊖1	25 ℃	30	80	-	Dog		1,2
Angle	Φ	230	60	85	-	Deg.	-	1,2
Contrast Ratio	Cr	25 ℃	2	5.3	5.9	-	⊖=0° ⊕=0°	3
Response	Т.	25 ℃	-	91	250		⊖=0°	4
Time(rise)	Tr	0 °C	-	950	1150	ms	⊕=0°	4
Response	Τf	25 ℃	-	151	250		⊖=0°	4
Time(fall)	Tf	0 °C	-	950	1150	ms	⊕=0°	4

5. ELECTRO - OPTICAL CHARACTERISTICS

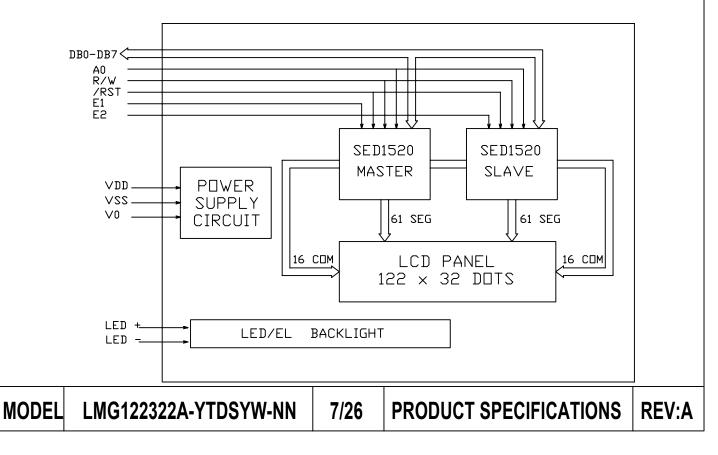


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6. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

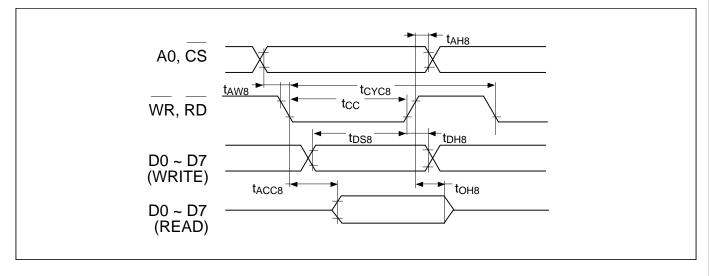
		INCTION DESCRIPTION
PIN NO.	SYMBOL	FUNCIONS
1	VSS	Ground
2	VDD	Power supply for logic circuit(5.0V)
3	V0	Operating voltage for LCD driving(Variable)?CONTRAST ADJUST
4		Input, Usually connected to the low-order bit of the MPU address bus
	A0	and used to indentify the data or command
		A0=0:D0-D7 are display control data
		A0=1: D0-D7 are display data
5	E1	Chip Selection Signal for IC1
6	E2	Chip Selection Signal for IC2
7	R/W	Used as input pins of read control signal (if R\W is high) or write
		control signal (if low)
8-15	DB0-DB7	Three-state I/O The 8-bit bi-directional data buses to be connected to
		the 8-or 16-bit standard MPU data buses
16		Input ,the system is reset during edge sense of the signal. the interface
		type to the 68-series or 80-series MPU is selected by the level input as
	RST	follows :
		High level: 68 series MPU interface
		Low level: 80 series MPU interface
17	А	Backlight (+) 5.0V
18	K	Backlight (-)

6-2.BLOCK DIAGRAM



7 TIMING CHARACTERISTICS

7.1 System Bus Read/Write I (80 Family MPU)



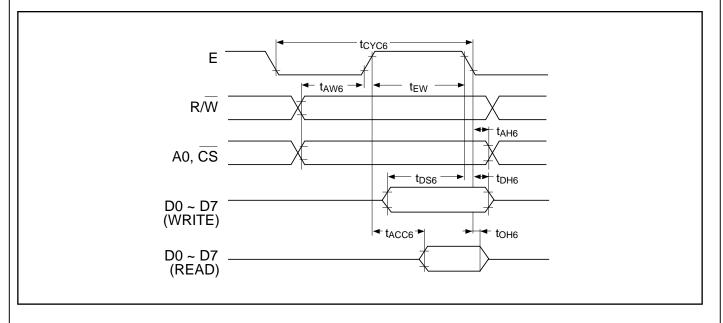
Ta = -20 to 75° C, Vss = -5.0V \pm 10%, Unit: ns

Signal	Symbol	Parameter	Min.	Max.	Condition
	t AH8	Address hold time	10		
A0, CS	t AW8	Address setup time	20		
	t CYC8	System cycle time	1000		
WR, RD	t cc	Control pulse width	200		
	t DS8	Data setup time	80		
	t DH8	Data hold time	10		
D0–D7	t ACC8	RD access time		90	CL = 100pF
	t OH8	Output disable time	10	60	

*1. Each of the values where Vss = -3.0V is about 200% of that where Vss = -5.0V (i.e., the listed value).

*2. The rise or fall time of input signals should be less than 15 ns.

7.2 System Bus Read/Write II (68 Family MPU)



Ta = -20 to 75° C, Vss = -5.0V \pm 10%, Unit: ns

Signal	Symbol	Parameter	Parameter			Condition
A0, CS	t CYC6* ¹	System cycle time	1000			
R/W	t AW6	Address setup time				
	t AH6	Address hold time	Address hold time			
D0–D7	t DS6	Data setup time	Data setup time			
	t DH6	Data hold time		10		
	tOH6	Output disable time		10	60	CL = 100pF
	t ACC6	Access time			90	
E	t EW	Enable pulse width Read		100		
			Write	80		

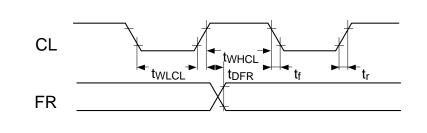
*1. t CYC6 indicates the cycle time during which CS•E = "H". It does not mean the cycle time of signal E.

*2. Each of the values where Vss = -3.0V is about 200% of that where Vss = -5.0V (i.e., the listed value).

*3. The rise or fall time of input signals should be less than 15 ns.

8/26 **PRODUCT SPECIFICATIONS**

7.3 Display Control Timing



7.3.1 Input Timing

Ta = -20 to 75°C, Vss = $-5.0V \pm 10\%$ Unit: μ s (twLcL, twHcL, tDFR), ns (tr, tf)

		-		• •	, ,	<u>,</u>
Signal	Symbol	Parameter	Min.	Тур.	Max.	Condition
CL	tWLCL	Low level pulse width	35			
	tWHCL	High level pulse width	35			
	tr	Rise time		30	150	
	tf	Fall time		30	150	
FR	tDFR	FR delay time	-2.0	0.2	2.0	

7.3.2 Output Timing

Ta = –20 to 75°C, Vss = –5.0V \pm 10%, Unit: μs

Signal	Symbol	Parameter	Min.	Тур.	Max.	Condition
FR	tDFR	FR delay time		0.2	0.4	CL = 100pF

*1. The listed FR input delay time applies to the SED1520 and SED15200 (slave).

The listed FR output delay time applies to the SED1520 (master).

*2. Each of the values where Vss = -3.0V is about 200% of that where Vss = -5.0V (i.e., the listed value).

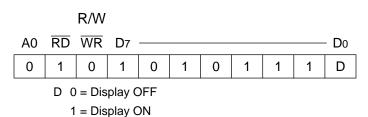
8. INSTRUCTION SET

Table 3 lists the commands used with the LMG122322A. This LSI uses a combination of A0, $R\overline{W}$ (RD, \overline{WR}) to identify a data bus signal. Interpretation and execution of a command depends not on external clock but on internal timing alone. Therefore, a command can be executed so fast that no busy check is needed.

A detailed description of commands follows.

8.1 DISPLAY ON/OFF

This command forces all display to turn on or off.



8.2 DISPLAY START LINE

This command specifies a line address thus marking the display line that corresponds to COM0. Display begins with the specified line address and covers as many lines as match the display duty in address ascending order. Dynamic line address change with the Display Start Line command enables column-wise scrolling or page change.

R/W

A0	RD	WR	D7							- D0
0	1	0	1	1	0	A4	Аз	A2	A1	A0
			-			– High	n-orde	r bits		

A4	A3	A2	A1	A0	Line address
0	0	0	0	0	0
0	0	0	0	1	1
		—			_
		_			—
1	1	1	1	1	31

8.3 SET PAGE ADDRESS

This command is used to specify a page address equivalent to a row address for MPU access to the display data RAM. A required bit of the display data RAM can be accessed by specifying its page address and column address. Changing the page address causes no change in display.

R/W

A0	RD	WR	D7				1			D0	
0	1	0	1	0	1	1	1	0	A1	Ao	
				Pag	je						
	0 0						0				
	0			1				1			
	1		0					2			
	1		1					3			

8.4 **COLUMN ADDRESS**

This command specifies a display data RAM column address. The column address is incremented by 1 each time the MPU accesses from the set address to the display data RAM. Thus, it is possible for the MPU to gain continuous access to only the data. This incrementing stops with address 80; the page address is not continuously changed.

D0

A0

R/W

RD WR D7 0

A0

0

1

0 A6 A5 A4 Аз A2 A1

A6	A5	A4	A3	A2	A1	A0	Column address
0	0	0	0	0	0	0	0
0	0	0	0	0	0	1	1
			_				
			_				_
1	0	0	1	1	1	1	79

PRODUCT SPECIFICATIONS

8.5 READ STATUS

R/W

A0	RD	WR	D7							D0	
0	0	1	Busy	ADC	ON/ OFF	Reset	0	0	0	0	

- BUSY: BUSY being "1" means that system is performing an internal operation or is reset. No command is accepted before BUSY = "0". As long as the cycle time requirement is met, no BUSY check is needed.
- ADC: Indicates assignment of column addresses to segment drivers.
 - 0: Inverted (column address 79-n \leftrightarrow segment driver n)
 - 1: Forward (column address $n \leftrightarrow$ segment driver n)
- ON/OFF: Indicates display on or off.
 - 0: Display on
 - 1: Display off

This bit has polarity reverse to the Display ON/OFF command.

- RESET: Indicates that system is being initialized by the RES signal or the Reset command.
 - 0: Display mode
 - 1: Being reset

8.6 WRITE DISPLAY DATA

This command allows the MPU to write 8 bits of data into the display data RAM. Once the data is written, the column address is automatically incremented by 1; this enables the MPU to write multi-word data continuously.

 A0
 RD
 R/W
 D7
 D0

 1
 1
 0
 Write data

8.7 READ DISPLAY DATA

This command allows the MPU to read 8 bits of data from the display data RAM location specified by a column address and a page address. Once the data is read, the column address is automatically incremented by 1; this enables the MPU to read multi-word data continuously.

A dummy read is needed immediately after the column address is set. For details, see 3. (1)–(c).??

		R/W		
_A0	RD	WR	D7	D0
1	0	1		Read data

8.8 SELECT ADC

This command inverts the relation of assignment between display data RAM column addresses and segment driver outputs. In other words, the Select ADC command can software-invert the order of segment driver output pins, reducing the restrictions on the configuration of ICs at LCD module assembly.

Incrementing the column address by 1, which takes place after the MPU writing or reading display data.

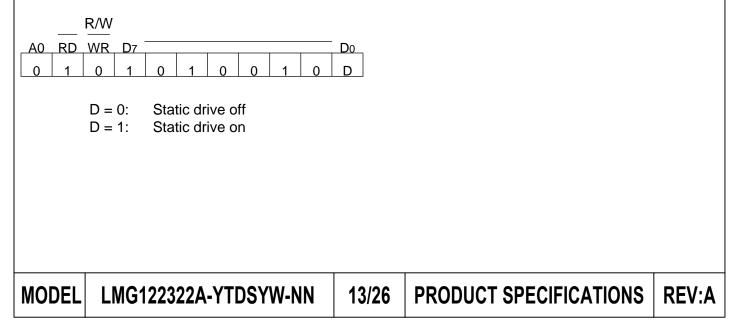
A0	RD	WR	D7	_			_			Do
0	1	0	1	0	1	0	0	0	0	D

D = 0: Clockwise output (forward)

D = 1: Counterclockwise output (reverse)

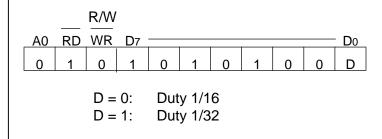
8.9 STATIC DRIVE ON/OFF

This command forces all display to be on and, at the same time, all common output to be selected.



8.10 SELECT DUTY

This command is used to select the duty (degree of multiplexity) of LCD driving.



8.11 READ MODIFY WRITE

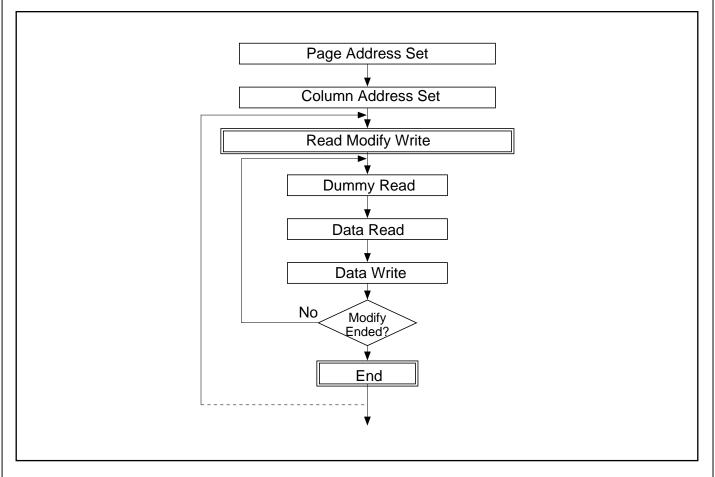
This command is used with the End command in a pair. Once it has been entered, the column address will be incremented not by the Read Display Data command but by the Write Display Data command only. This mode will stay until the End command is entered.

Entry of the End command causes the column address to return to the address which was valid when the Read Modify Write command was entered. This function lessens the load of the MPU when the data in a specific display area are repeatedly updated (as blinking cursor).

		R/W								
A0	RD	RD	D7							Do
0	1	0	1	1	1	0	0	0	0	0

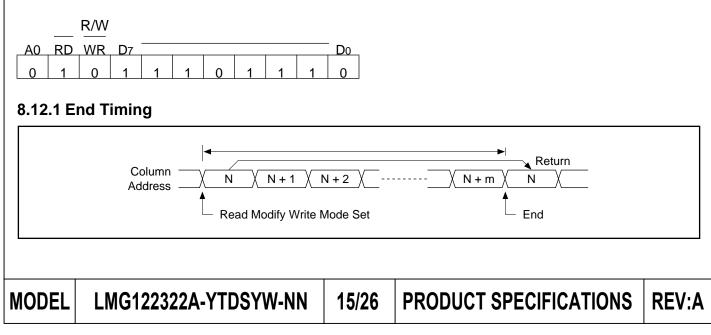
Even in the Read Modify Write mode, any command other than Read/Write Data and Set Column Address may be used.

8.11 Cursor Blinking Sequence



8.12 END

This command cancels the Read Modify Write command, returning the column address to the initial mode address.



8.13 RESET

This command initializes the display start line register, column address counter, and page address counter without any effect on the display data RAM.

The reset operation follows entry of the Reset command.

			R/W								
A	0	RD	WR	D7			•				Do
C)	1	0	1	1	1	0	0	0	1	0

Initialization at power-on is performed not by the Reset command but by a reset signal applied to the RES pin.

8.14 SAVE POWER (COMBINED COMMAND)

Static drive going on with display off invokes power-saving mode, reducing current consumption to nearly static current level. During this mode, the LMG122322A holds the following conditions:

(a) It stops driving the LCD; the segment and common driver outputs are at VDD level.

(b) Oscillation and external clock input are disabled; OSC2 is in floating condition.

(c) The display data and operational mode are held.

The power-saving mode is cancelled by display on or static drive off.

If an external resistor division circuit is used to give LCD driving voltage level, the current flowing into the resistors must be cut off by the power-save signal.

8.14.1 External Resistor Division Circuit

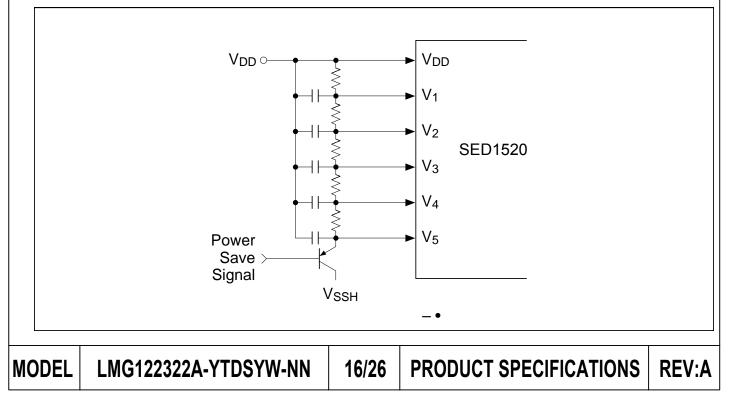


Table 3 Commands

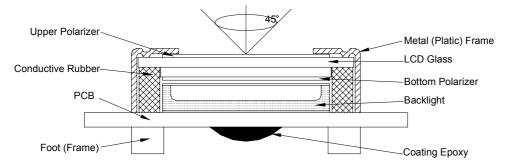
	Command	Code									Function			
	Command	A0	RD	WR	D7	D6	D5	D4	D3	D2	D1	D0	i dilotion	
(1)	Display ON/OFF	0	1	0	1	0	1	0	1	1	1	0/1	Turns all display on or off, independently of dis- play RAM data or internal status. 1: ON 0: OFF (Power-saving mode with static drive on)	
(2)	Display start line	0	1	0	1	1	0	Disp	-	Start		ress	Specifies RAM line corresponding to uppermost line (COM0) of display.	
(3)	Set page address	0	1	0	1	0	1	1	1	0		age –3)	Sets display RAM page in page address registe	
(4)	Set column (segment) address	0	1	0	0		Colu	mn A	ddre	ess (0–79)	Sets display RAM column address in column address register.	
(5)	Read status	0	0	1	Busy	ADC	ON/OFF	RESET	0	0	0	0	Reads the following status:BUSY1: Internal operation, 0: ReadyADC1: CW output (forward), 0: CCW output (reverse)ON/OFF1: Display off, 0: Display on RESETRESET1: Being reset, 0: Normal	
(6)	Write display data	1	1	0			Ņ	Nrite	Dat	a			Writes data from data bus into display RAM. Display RAM location whose address has be preset is accessed. Af	
(7)	Read display data	1	0	1	Read Data					Reads data from display RAM onto data bus. access, the column address is incremented by 1.				
(8)	Select ADC	0	1	0	1	0	1	0	0	0	0	0/1	Used to invert relationship of assignment between display RAM column addresses and segment driver outputs. 0: CW output (forward) 1: CCW output (reverse)	
(9)	Static drive ON/ OFF	0	1	0	1	0	1	0	0	1	0	0/1	Selects normal display or static driving operation 1: Static drive (power-saving mode) 0: Normal driving	
(10)	Select duty	0	1	0	1	0	1	0	1	0	0	0/1	Selects LCD cell driving duty.	
(11)	Read modify write	0	1	0	1	1	1	0	0	0	0	0	Increments column address counter by 1 when display data is written. (This is not done when data is read.)	
(12)	End	0	1	0	1	1	1	0	1	1	1	0	Clears read modify write mode.	
(13)	Reset	0	1	0	1	1	1	0	0	0	1	0	Sets display start line register on the first line. Also sets column address counter and page address counter to 0.	

MODEL

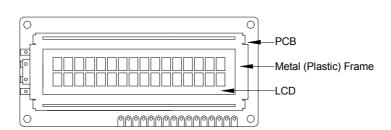
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9. QUALITY SPECIFICATIONS

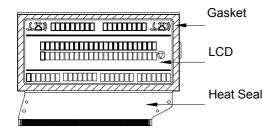
- 9 1. LCM Appearance and Electric inspection Condition
 - 1. Inspection will be done by placing LCM 30cm away from inspector's eyeballs under normal illumination.



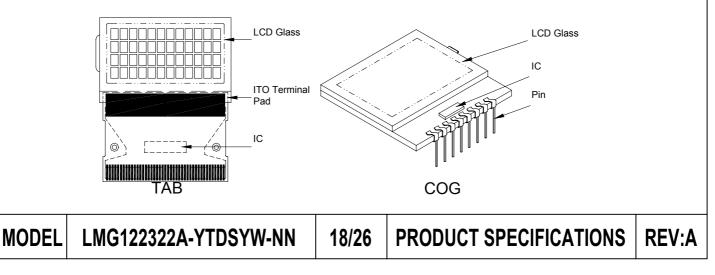
- 2. View Angle: with in 45° around perpendicular line.
- 9 2. Definition
 - 1. COB



2. Heat Seal



3. TAB and COG



9. QUALITY SPECIFICATIONS (Continued)

9-3. Sampling Plan and Acceptance

1.Sampling Plan

MIL - STD - 105E (\parallel) ordinary single inspection is used.

2. Acceptance

Major defect:	AQL = 0.25%
Minor defect:	AQL = 0.65%

9-4. Criteria

1.COB

Defect	Inspection Item	Inspection Standards		
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm ²	Reject	
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject	
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject	
Major	PCB cutting defect	Exceed the dimension of drawing	Reject	

2.SMT

ſ	Defect	Inspection Item	Inspection Standa	ards
-	Minor	Component marking not readable		Reject
	Minor	Component height	Exceed the dimension Of drawing	Reject
	Major	Component solder defect (missing , extra wrong component or wrong orientation	l,	Reject
	Minor	Component position shift x soldering pad x y	X < 3/4Z Y > 1/3D	Reject Reject
	Minor	Component tilt component p soldering pad	Y > 1/3D	Reject
	Minor	Insufficient solder component θ PAD PCB	<i>θ</i> <u>≤</u> 20°	Reject
ODEL	LMG12	22322A-YTDSYW-NN 19/26 PF	RODUCT SPECIFICAT	

9. QUALITY SECIFICATIONS (Continued)

9-4. Criteria (Continued)

3. Metal (Plastic) Frame

Defect	Inspection Item	li	nspection Standar	rds
Major	Crack / breakage	Any	/where	Reject
		W	L	Acceptable of Scratch
		w<0.1mm	Any	Ignore
		0.1 <u><</u> w<0.2mm	L <u><</u> 5.0mm	2
Minor	Frame Scratch	0.2 <u><</u> w<0.3mm	L <u><</u> 3.0mm	1
_		w <u>></u> 0.3mm	Any	0
		with distance g	criteria applicable reater than 5mm. ch on the back side ignored .	
				Acceptable of Dents / Pricks
		Ф <u><</u>	1.0mm	2
	Frame Dent , Prick	1.0<⊕ <u><</u> 1.5mm		1
Minor	$\Phi = \frac{L + W}{2}$	1.5	mm< Φ	0
	2	Note : 1. Above criteria applicable to any two dent / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (n visible) can be ignored		
Minor	Frame Deformation	Excee	d the dimension of	drawing
Minor	Metal Frame Oxidation		Any rust	

4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standards		
Minor	Tilted soldering	Within the angle +5°	Acceptable	
Minor	Uneven solder joint /bump		Reject	
Minor	Hole $\Phi = \frac{L + W}{2}$	Expose the conductive line	Reject	
MILIO	$\psi_{-} = \frac{1}{2}$	Φ > 1.0mm	Reject	
Minor	Position shift $Y \xrightarrow{-\psi} \xrightarrow{-\psi} D$	Y > 1/3D	Reject	
IVIIIIOI		X > 1/2Z	Reject	

9. QUALITY SPECIFICATIONS (Continued)

9-4. Criteria (Continued)

5. Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reje

6. Heatseal \land TCP \land FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	⊕> 0.5mm	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift $y - \frac{1}{\sqrt{-\frac{1}{2}}} = \frac{1}{\sqrt{-\frac{1}{2}}}$	Y > 1/3D	Reject
		X > 1/2Z	Reject
Major	Conductive line break		Reject

7. LED Backing Protective Film and Others

Defect	Inspection Item	Inspection Standards				
		Acceptable number of units				
		⊕ <u><</u> 0.10mm	Ignore			
		0.10<⊕ <u><</u> 0.15mm	2			
Minor	LED dirty, prick	0.15<⊕ <u><</u> 0.2mm	1			
		⊕>0.2mm	0			
		The distance between any two spots should be <u>></u> 5m Any spot/dot/void outside of viewing area is acceptal				
Minor	Protective film tilt	Not fully cover LCD	Reject			
Major	COG coating	Not fully cover ITO circuit	Reject			

8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

MODEL

9. QUALITY SPECIFICATIONS (Continued)

9-4. Criteria (Continued)

9. Inspection Specification of LCD

	Insp	ect Item		In	spectior	<u> </u>	Standard	S		
		* Glass Scratch	W	-	<u><</u> 0.03	0.	03 <w<u><0.0</w<u>	5 ۱	W>0.05	
	Linear Defect	* Polarizer Scratch	L		L<5		L<3		Any	
Minor		* Fiber and Linear	ACC. NO.	1			1		Reject	
		material		L is the length and W is the width of the defect				efect		
		* Foreign material	Φ	Ф <u><</u> 0.1		0.15	0.15<⊕ <u><</u> 0.	2	⊕>0.2	
	Black Spot and Polarizer Pricked	between glass and polarizer or glass	ACC. NO.	3EA / 100mm ²	2 2		1		0	
Minor		and glass * Polarizer hole or protuberance by external force	Note	Note Φ is the average diameter of the defect. Distance between two defects > 10mm.						
	White Spot and Bubble in polarizer	 * Unobvious transparant foreign material between glass and glass or glass and polarizer * Air protuberance between polarizer and glass 	Φ	⊕ <u><</u> 0.3		0.3	0.3<⊕ <u><</u> 0.5		. 5 <Φ	
			ACC. NO.	3EA / 7	100mm ² 1		1		0	
Minor			Note	Φ is the average diameter of the defect. Distance between two defects > 10mm.						
Minor	Segment Defect		Φ	Ф <u><</u> 0.10	0.10 <⊕	0.10<⊕ <u><</u> 0.20		0.20<⊕ <u><</u> 0.25		
			ACC. NO.	3EA / 100mm ²	2		1		0	
				W is mor	<i>W</i> is more than 1/2 segment width Reject					
			Note	ote $\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm						
			Φ	Ф <u><</u> 0.10	0.10 0.10<⊕ <u><</u> 0.		0.20 0.20<⊕ <u><</u> 0.2		⊕>0.2	
Minor	Protuberant Segment		W	Glue	W <u><</u> 1/2 W <u><</u> 0		W <u><</u> 1/2 S W <u><</u> 0.		Ignore	
	Cogmon	Φ = (L + W) / 2	ACC. NO.	3EA / 100mm ²			1		0	
			1. Segment							
Minor	Assembly Mis-alignment		E	B B <u><</u> 0.4mm		0.4<	0.4 <b<u><1.0mm</b<u>		B>1.0mm	
			B-	A B-A<1/2B		B	B-A<0.2		B-A<0.25	
			Juc	lge Acceptable			Acceptable Acc		cceptable	
			2. Dot Matrix							
			Deformation>2° Reject							
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"							
				1						
. LN	1040000A V	YTDSYW-NN	22/26		ראווחה	' CD	ECIFIC/	۸ TI/	ONIC	

10. RELIABILITY

NO.	ltem	Condition	Criterion				
1	High Temperature Operating	70℃, 240Hrs					
2	Low Temperature Operating	- 2 0 ℃, 240Hrs					
3	High Humidity	60℃, 90%RH, 96Hrs	No defect in cosmetic and operational function allowable.				
4	High Temperature Storage	80℃, 240Hrs					
5	Low Temperature Storage	-30℃, 240Hrs					
6		Random wave					
	Vibration	Vibration					
	Vibration	Acceleration: 2g					
		2 Hrs per direction(X,Y,Z)					
7		-30℃ to 25℃ to 80℃					
	Thermal Shock	(60Min) (5Min) (60Min)					
		10Cycles					
8	ESD Tosting	Contract Discharge Voltage: +1 ~ 5kV and –1 ~ –5kV	There will be discharged ten times at every discharging voltage cycle. The voltage gap is 1kV.				
	ESD Testing	Air Discharge Voltage: +1 ~ 8kV and –1 ~ -8kV					

Note: 1) Above conditions are suitable for GOLDENTEK standard products.

2) For restrict products, the test conditions listed as above must be revised.

11. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(1) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface.

Do not use the following solvent:

- Water
- Ketone
- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
 - Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
 - To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
 - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.

11. HANDLING PRECAUTION (Continued)

- Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them.

However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.

- If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
- A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.

Usage under the relative condition of 40°C, 50%RH or less is reequired.

(6) Storage

In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.

- Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
 - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.
 - Which should be burned up later.
 - When any liquid crystal leaked out of a damaged glass cell comes in contact with your hands, please wash it off well with soap and water.

